

IN THE CLAIMS:

Please amend claim 14 as follows:

D2 14. (Thrice Amended) A semiconductor device comprising a semiconductor chip, a tape for mounting said semiconductor chip thereto, an adhesive resin layer interposed between said semiconductor chip and said tape, and solder balls arranged on said tape, characterized in that said tape has no vapor escape holes formed therein, and is of a material having high water permeability of  $10 \text{ g/m}^2 \cdot 24\text{H}$  or more, sufficient to prevent cracking and bulging of said semiconductor device which might occur when the solder balls are reflowed after said semiconductor device absorbs moisture.